



Material Content Data Sheet



Sales Product Name		IPA90R1K0C3		Issued		29. August 2013		
MA#		MA000468304						
Package		PG-TO220-3-111		Weight*		2171.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.558	0.26	0.26	2559	2559
leadframe	non noble metal	iron	7439-89-6	1.407	0.06		648	
	inorganic material	phosphorus	7723-14-0	0.422	0.02		194	
	non noble metal	copper	7440-50-8	1404.801	64.69	64.77	646925	647767
wire	non noble metal	aluminium	7429-90-5	1.580	0.07	0.07	728	728
encapsulation	organic material	carbon black	1333-86-4	1.422	0.07		655	
	plastics	epoxy resin	-	133.670	6.16		61557	
	inorganic material	silicondioxide	60676-86-0	575.921	26.52	32.75	265217	327429
leadfinish	non noble metal	tin	7440-31-5	42.925	1.98	1.98	19767	19767
plating	non noble metal	nickel	7440-02-0	0.732	0.03		337	
	inorganic material	phosphorus	7723-14-0	0.002	0.00	0.03	1	338
solder	non noble metal	tin	7440-31-5	1.994	0.09		918	
	noble metal	silver	7440-22-4	0.767	0.04		353	
	non noble metal	antimony	7440-36-0	0.307	0.01	0.14	141	1413
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com